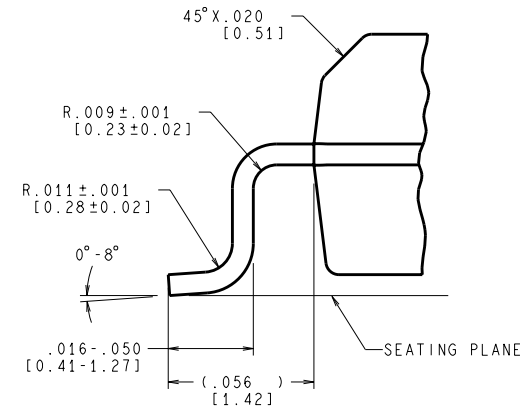
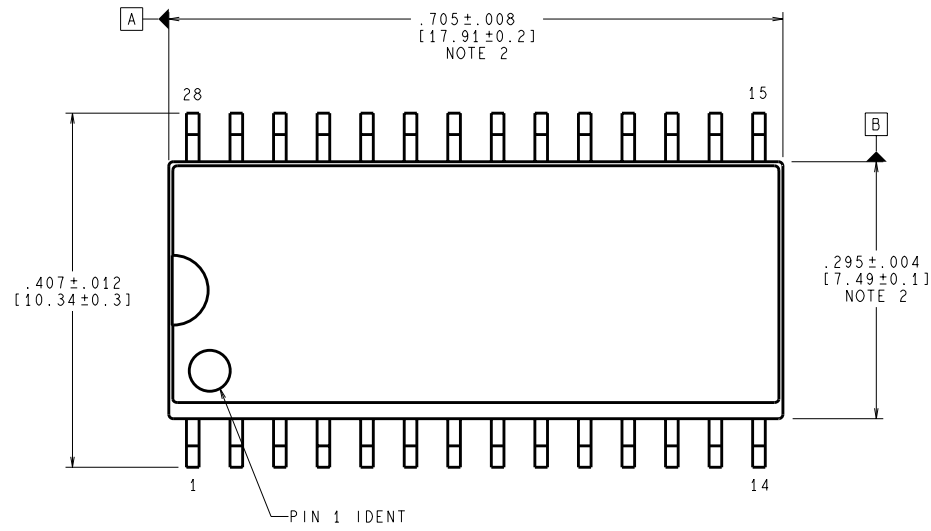
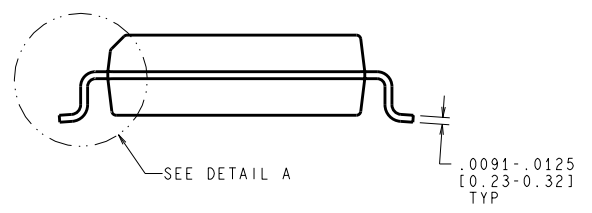
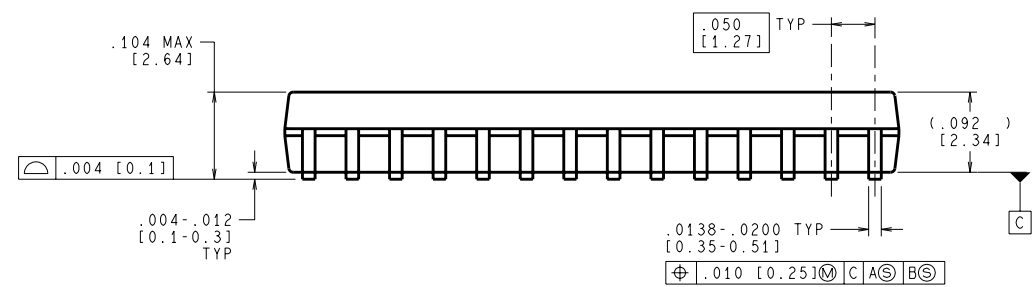


| REVISIONS | | | | |
|-----------|---|--------|------------|----------|
| LTR | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| B | UPDATE LEAD SHAPE; REDRAW PER CURRENT STD | 11816 | 11/24/1997 | TL/ |



DETAIL A
TYPICAL, SCALE: 30X



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH TO BE 200 MICRONS/ 5.08 MICROMETERS MINIMUM LEAD/TIN(SOLDER) ON COPPER.
 - DIMENSION DOES NOT INCLUDE MOLD FLASH.
 - REFERENCE JEDEC REGISTRATION MS-013, VARIATION AE, DATED MAY 1990.

| | | | | |
|---------------------|------------|--|------|----------------|
| APPROVALS | DATE | National Semiconductor | | |
| DRAWN T. LEQUANG | 11/24/1997 | 2900 Semiconductor dr., Santa Clara, CA 95052-8090 | | |
| DTG. CHK. | | MOLDED PACKAGE, SO, .300 WIDE, 28 LEAD | | |
| ENGR. CHK. | | | | |
| PROJECTION | | SCALE | SIZE | DRAWING NUMBER |
| INCH [MM] | | N/A | C | (SC)MKT-M28B |
| | | DO NOT SCALE DRAWING | | REV B |
| | | SHEET 1 of 1 | | |